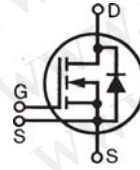


Polar™ HiPerFET™ Power MOSFET

IXFN300N10P

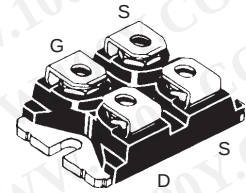
N-Channel Enhancement Mode
 Avalanche Rated
 Fast Intrinsic Diode



$$\begin{aligned} V_{DSS} &= 100V \\ I_{D25} &= 295A \\ R_{DS(on)} &\leq 5.5m\Omega \\ t_{rr} &\leq 200ns \end{aligned}$$

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	$T_J = 25^\circ\text{C}$ to 175°C	100	V
V_{DGR}	$T_J = 25^\circ\text{C}$ to 175°C , $R_{GS} = 1M\Omega$	100	V
V_{GSS}	Continuous	± 20	V
V_{GSM}	Transient	± 30	V
I_{D25}	$T_C = 25^\circ\text{C}$	295	A
I_{LRMS}	External Lead Current Limit	200	A
I_{DM}	$T_C = 25^\circ\text{C}$, Pulse Width Limited by T_{JM}	900	A
I_A	$T_C = 25^\circ\text{C}$	100	A
E_{AS}	$T_C = 25^\circ\text{C}$	3	J
dv/dt	$I_S \leq I_{DM}$, $V_{DD} \leq V_{DSS}$, $T_J \leq 175^\circ\text{C}$	20	V/ns
P_D	$T_C = 25^\circ\text{C}$	1070	W
T_J		-55 ... +175	$^\circ\text{C}$
T_{JM}		175	$^\circ\text{C}$
T_{stg}		-55 ... +175	$^\circ\text{C}$
T_L	1.6mm (0.062 in.) from Case for 10s	300	$^\circ\text{C}$
V_{ISOL}	50/60 Hz, RMS $I_{ISOL} \leq 1\text{mA}$	$t = 1\text{min}$ 2500 $t = 1\text{s}$ 3000	V~ V~
M_d	Mounting Torque Terminal Connection Torque	1.5/13 1.3/11.5	Nm/lb.in Nm/lb.in
Weight		30	g

miniBLOC
E153432



G = Gate
 S = Source
 D = Drain

Either Source terminal at miniBLOC can be used as Main or Kelvin Source

Features

- International Standard Package
- miniBLOC, with Aluminium Nitride Isolation
- Low $R_{DS(on)}$ and Q_G
- Avalanche Rated
- Low Package Inductance
- Fast Intrinsic Rectifier

Advantages

- High Power Density
- Easy to Mount
- Space Savings

Applications

- DC-DC Converters
- Battery Chargers
- Switch-Mode and Resonant-Mode Power Supplies
- DC Choppers
- AC and DC Motor Drives
- Uninterrupted Power Supplies
- High Speed Power Switching Applications

Symbol	Test Conditions	Characteristic Values		
	($T_J = 25^\circ\text{C}$, Unless Otherwise Specified)	Min.	Typ.	Max.
BV_{DSS}	$V_{GS} = 0V$, $I_D = 3\text{mA}$	100		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 8\text{mA}$	2.5		5.0 V
I_{GSS}	$V_{GS} = \pm 20V$, $V_{DS} = 0V$			± 200 nA
I_{DSS}	$V_{DS} = V_{DSS}$, $V_{GS} = 0V$			25 μA
	$T_J = 150^\circ\text{C}$			1.5 mA
$R_{DS(on)}$	$V_{GS} = 10V$, $I_D = 50A$, Note 1			5.5 m Ω

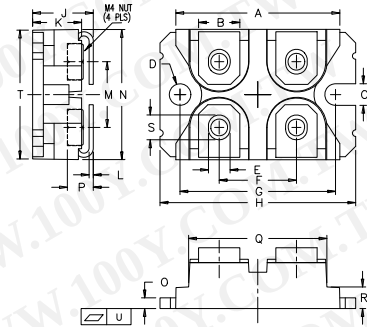
Symbol	Test Conditions	Characteristic Values		
		Min.	Typ.	Max.
g_{fs}	$V_{DS} = 10V, I_D = 60A$, Note 1	55	92	S
C_{iss}	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$		23	nF
C_{oss}			6100	pF
C_{rss}			417	pF
$t_{d(on)}$	Resistive Switching Times $V_{GS} = 10V, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 100A$ $R_G = 1\Omega$ (External)		36	ns
t_r			35	ns
$t_{d(off)}$			56	ns
t_f			25	ns
$Q_{g(on)}$	$V_{GS} = 10V, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 150A$		279	nC
Q_{gs}			84	nC
Q_{gd}			107	nC
R_{thJC}			0.14	$^{\circ}C/W$
R_{thCS}		0.05		$^{\circ}C/W$

Source-Drain Diode

Symbol	Test Conditions	Characteristic Values		
		Min.	Typ.	Max.
I_S	$V_{GS} = 0V$			300 A
I_{SM}	Repetitive, Pulse Width Limited by T_{JM}			1000 A
V_{SD}	$I_F = 100A, V_{GS} = 0V$, Note 1			1.3 V
t_{rr}	$I_F = 150A, -di/dt = 100A/\mu s$ $V_R = 50V$	0.71	200	ns
Q_{RM}				μC
I_{RM}				A

Note 1: Pulse test, $t \leq 300\mu s$, duty cycle, $d \leq 2\%$.

SOT-227B Outline (IXFN)



SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.240	1.255	31.50	31.88
B	.307	.323	7.80	8.20
C	.161	.169	4.09	4.29
D	.161	.169	4.09	4.29
E	.161	.169	4.09	4.29
F	.587	.595	14.91	15.11
G	1.186	1.193	30.12	30.30
H	1.496	1.505	38.00	38.23
J	.460	.481	11.68	12.22
K	.351	.378	8.92	9.60
L	.030	.033	0.76	0.84
M	.496	.506	12.60	12.85
N	.990	1.001	25.15	25.42
O	.078	.084	1.98	2.13
P	.195	.235	4.95	5.97
Q	1.045	1.059	26.54	26.90
R	.155	.174	3.94	4.42
S	.186	.191	4.72	4.85
T	.968	.987	24.59	25.07
U	-.002	.004	-0.05	0.1

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:	4,835,592	4,931,844	5,049,961	5,237,481	6,162,665	6,404,065 B1	6,683,344	6,727,585	7,005,734 B2	7,157,338B2
	4,860,072	5,017,508	5,063,307	5,381,025	6,259,123 B1	6,534,343	6,710,405 B2	6,759,692	7,063,975 B2	
	4,881,106	5,034,796	5,187,117	5,486,715	6,306,728 B1	6,583,505	6,710,463	6,771,478 B2	7,071,537	

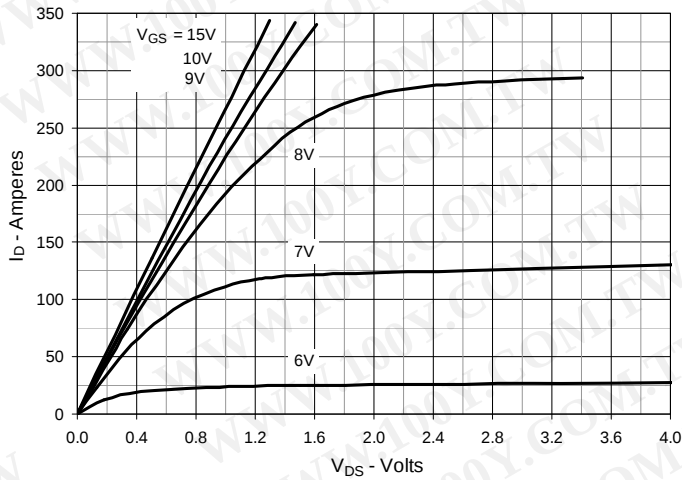
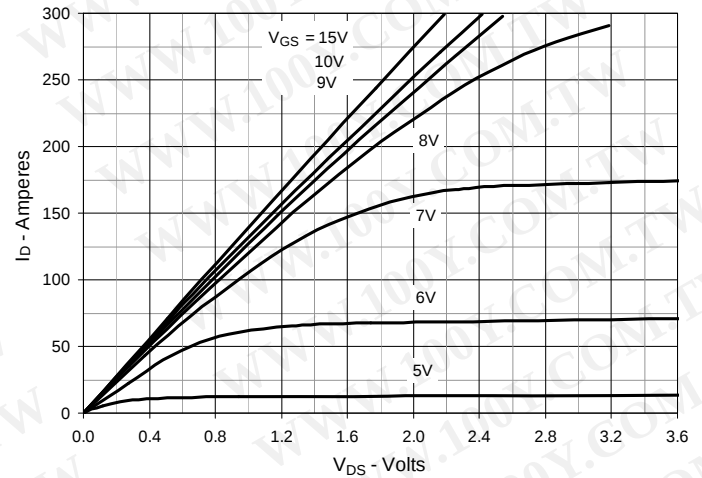
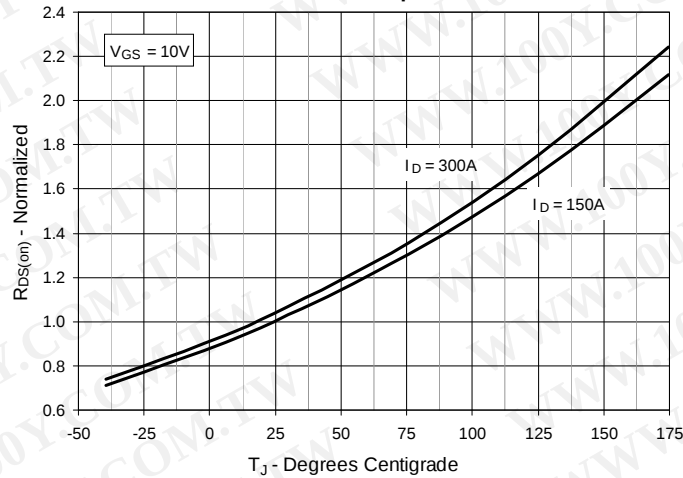
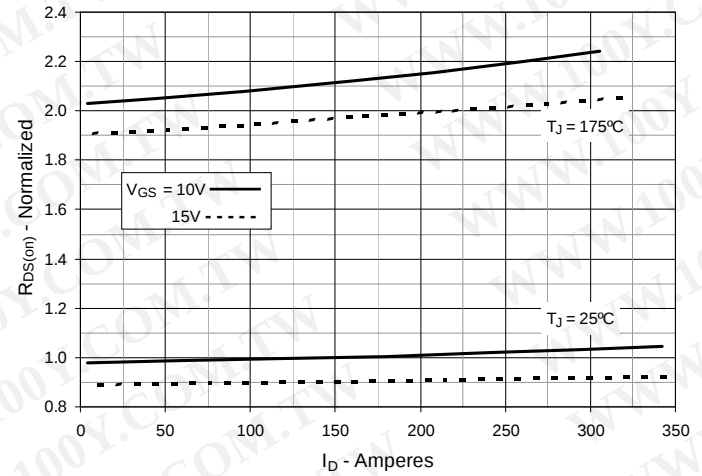
Fig. 1. Extended Output Characteristics @ $T_J = 25^\circ\text{C}$ Fig. 2. Output Characteristics @ $T_J = 150^\circ\text{C}$ Fig. 3. $R_{DS(on)}$ Normalized to $I_D = 150\text{A}$ Value vs. Junction TemperatureFig. 4. $R_{DS(on)}$ Normalized to $I_D = 150\text{A}$ Value vs. Drain Current

Fig. 5. Maximum Drain Current vs. Case Temperature

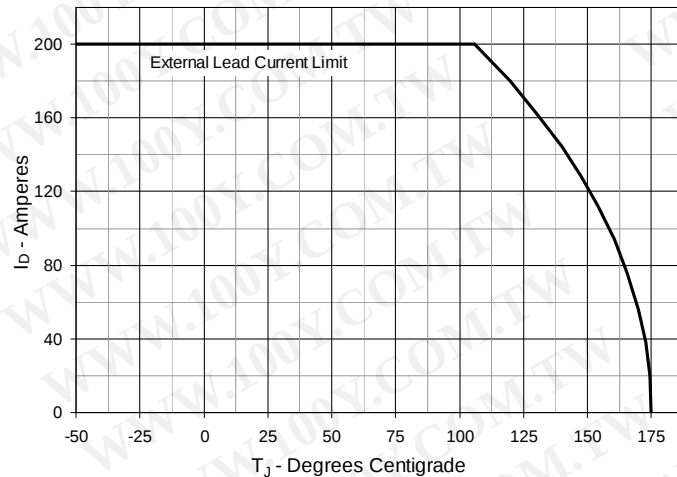


Fig. 6. Input Admittance

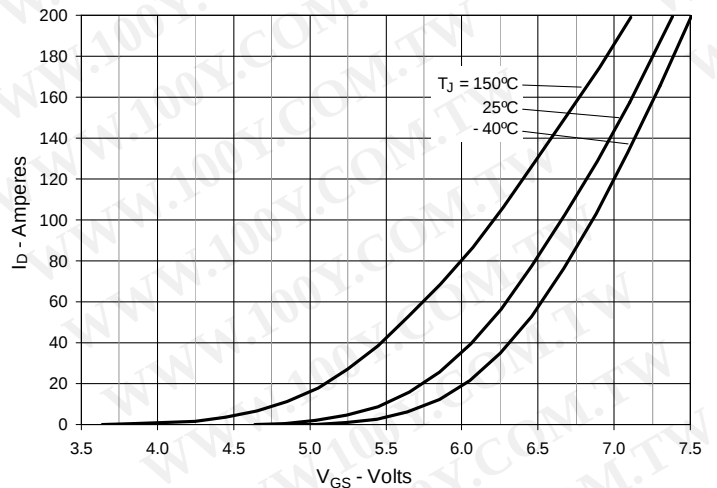


Fig. . Transconductance

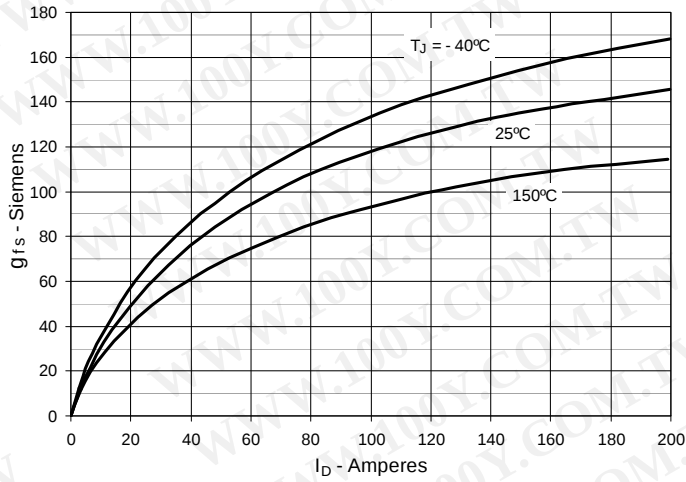


Fig. 8. Forward Voltage Drop of Intrinsic Diode

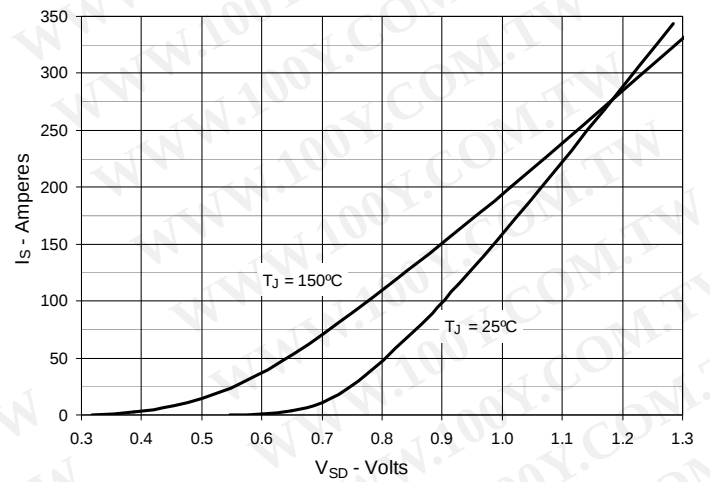


Fig. 9. Gate Charge

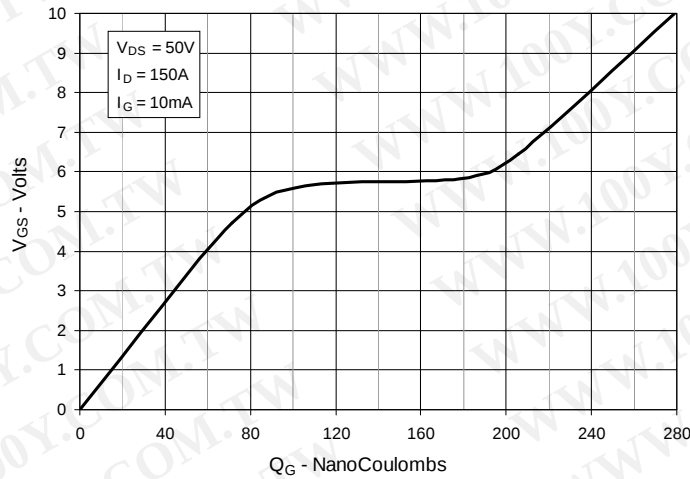


Fig. 10. Capacitance

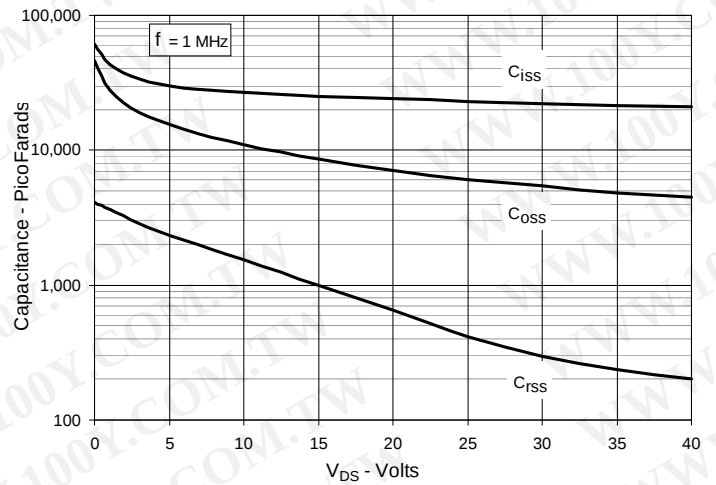


Fig. 11. Forward-Bias Safe Operating Area

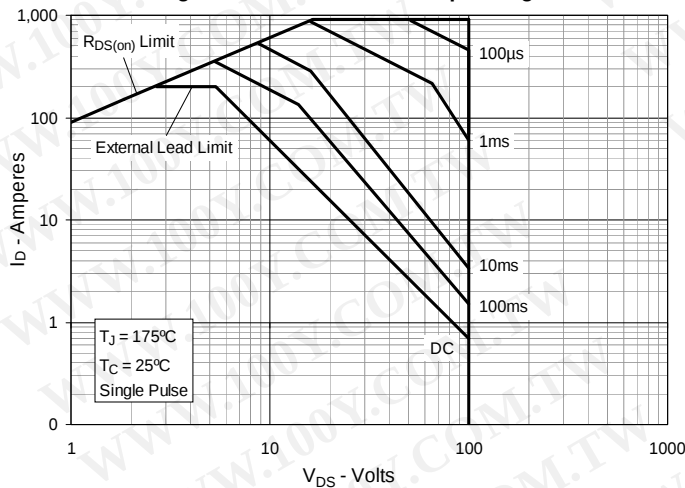


Fig. 12. Maximum Transient Thermal Impedance

